

Cool MOS™ Power Transistor

Feature

- New revolutionary high voltage technology
- Ultra low gate charge
- Periodic avalanche rated
- Extreme dv/dt rated
- High peak current capability
- Intrinsic fast-recovery body diode
- Extreme low reverse recovery charge
- Pb-free lead plating; RoHS compliant; Halogen free mold compound
- Qualified for industrial grade applications according to JEDEC⁰⁾

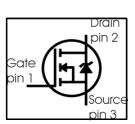
Туре	Package	Ordering Code	Marking
SPW20N60CFD	PG-TO247	Q67040-S4617	20N60CFD

Maximum Ratings

Parameter	Symbol	Value	Unit
Continuous drain current	I _D		Α
T _C = 25 °C		20.7	
<i>T</i> _C = 100 °C		13.1	
Pulsed drain current, t_p limited by T_{jmax}	<i>I</i> _{D puls}	52	
Avalanche energy, single pulse	E _{AS}	690	mJ
<i>I</i> _D = 10 A, <i>V</i> _{DD} = 50 V			
Avalanche energy, repetitive t_{AR} limited by T_{jmax} 1)	E _{AR}	1	
$I_{\rm D}$ = 20 A, $V_{\rm DD}$ = 50 V			
Avalanche current, repetitive t_{AR} limited by T_{jmax}	I _{AR}	20	Α
Reverse diode d <i>v</i> /d <i>t</i>	dv/dt	40	V/ns
/ _S =20.7A, V _{DS} =480V, 7 _j =125°C			
Gate source voltage	V _{GS}	±20	V
Gate source voltage AC (f >1Hz)	V _{GS}	±30	
Power dissipation, $T_{\rm C}$ = 25°C	P _{tot}	208	W
Operating and storage temperature	T _i , T _{stg}	-55 +150	°C

V _{DS} @ T _{imax}	650	V
R _{DS(on)}	0.22	Ω
I _D	20.7	Α





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Maximum Ratings

Parameter	Symbol	Value	Unit
Drain Source voltage slope	d <i>v</i> /dt	80	V/ns
V _{DS} = 480 V, <i>I</i> _D = 20.7 A, <i>T_j</i> = 125 °C			
Maximum diode commutation speed	d <i>i≓</i> dt	900	A/µs
V _{DS} = 480 V, / _D = 20.7 A, T _j = 125 °C			

Thermal Characteristics

Parameter	Symbol	Values		Unit	
		min.	typ.	max.	
Thermal resistance, junction - case	R _{thJC}	-	-	0.6	K/W
Thermal resistance, junction - ambient, leaded	R _{thJA}	-	-	62	
Soldering temperature, wavesoldering	T _{sold}	-	-	260	°C
1.6 mm (0.063 in.) from case for 10s					

Electrical Characteristics, at Tj=25°C unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Drain-source breakdown voltage	V _{(BR)DSS}	VGS=0V, /D=0.25mA	600	-	-	V
Drain-Source avalanche	V _{(BR)DS}	V _{GS} =0V, / _D =20A	-	700	-	
breakdown voltage						
Gate threshold voltage	V _{GS(th)}	/D=1000μA, VGS=VDS	3	4	5	
Zero gate voltage drain current	IDSS	V _{DS} =600V, V _{GS} =0V,				μA
		<i>T</i> j=25℃,	-	2.1	-	
		<i>T</i> j=150℃	-	1700	-	
Gate-source leakage current	I _{GSS}	V _{GS} =20V, V _{DS} =0V	-	-	100	nA
Drain-source on-state resistance	R _{DS(on)}	VGS=10V, /D=13.1A,				Ω
		<i>T</i> j=25℃	-	0.19	0.22	
		<i>Т</i> ј=150°С	-	0.51	-	
Gate input resistance	R _G	<i>f</i> =1MHz, open Drain	-	0.54	-	



Parameter	Symbol	Conditions		Values		Unit
			min.	typ.	max.	
Transconductance	g _{fs}	V _{DS} ≥2*/ _D * <i>R</i> _{DS(on)max} , / _D =13.1A	-	17.5	-	S
Input capacitance	C _{iss}	V _{GS} =0V, V _{DS} =25V,	-	2400	-	pF
Output capacitance	C _{oss}	<i>f</i> =1MHz	-	780	-	
Reverse transfer capacitance	C _{rss}		-	50	-	
Effective output capacitance, ²⁾ energy related	C _{o(er)}	V _{GS} =0V, V _{DS} =0V to 480V	-	83	-	pF
Effective output capacitance, ³⁾ time related	C _{o(tr)}		-	160	-	
Turn-on delay time	t _{d(on)}	V _{DD} =380V, V _{GS} =0/10V,	-	12	-	ns
Rise time	<i>t</i> r	/ _D =20.7A, <i>R</i> _G =3.6Ω	-	15	-	
Turn-off delay time	t _{d(off)}		-	59	-	
Fall time	<i>t</i> f		_	6.4	-	

Electrical Characteristics, at $T_i = 25$ °C, unless otherwise specified

Gate Charge Characteristics

Gate to source charge	Q _{gs}	V _{DD} =480V, / _D =20.7A	-	15	-	nC
Gate to drain charge	Q _{gd}		-	54	I	
Gate charge total	Qg	V _{DD} =480V, / _D =20.7A, V _{GS} =0 to 10V	-	95	124	
Gate plateau voltage	V _(plateau)	V _{DD} =480V, / _D =20.7A	-	7	-	V

⁰J-STD20 and JESD22

¹Repetitve avalanche causes additional power losses that can be calculated as $P_{AV} = E_{AR}^* f$.

 $^{2}C_{o(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} . $^{3}C_{o(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

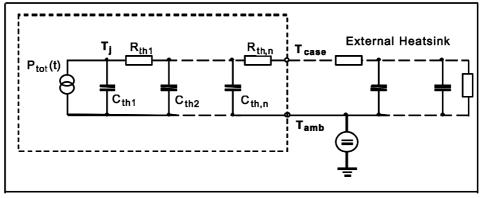


Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Inverse diode continuous forward current	I _S	7 _C =25℃	-	-	20.7	A
Inverse diode direct current, pulsed	I _{SM}		-	-	52	
Inverse diode forward voltage	V _{SD}	V _{GS} =0V, / _F =/ _S	-	1	1.2	V
Reverse recovery time	t _{rr}	V _R =480V, / _F =/ _S ,	-	150	-	ns
Reverse recovery charge	Q _{rr}	di _F /dt=100A/µs	-	1	-	μC
Peak reverse recovery current	<i>I</i> rrm		-	13	-	Α
Peak rate of fall of reverse recovery current	di _{rr} /dt		-	1400	-	A/µs

Electrical Characteristics, at $T_i = 25$ °C, unless otherwise specified

Typical Transient Thermal Characteristics

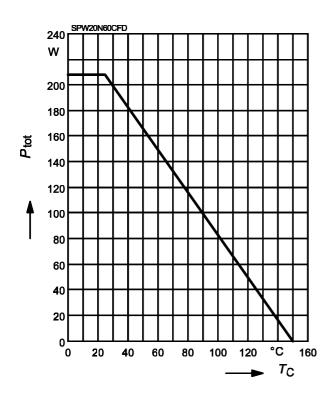
Symbol	Value	Unit	Symbol	Value	Unit
typ.			typ.		
Thermal re	esistance		Thermal ca	apacitance	
R _{th1}	0.007686	K/W	C _{th1}	0.0003764	Ws/K
R _{th2}	0.015		C _{th2}	0.001412	
R _{th3}	0.029		C _{th3}	0.001932	
R _{th4}	0.114		C _{th4}	0.005299	
R _{th5}	0.136		C _{th5}	0.012	
R _{th6}	0.059		C _{th6}	0.091	





1 Power dissipation

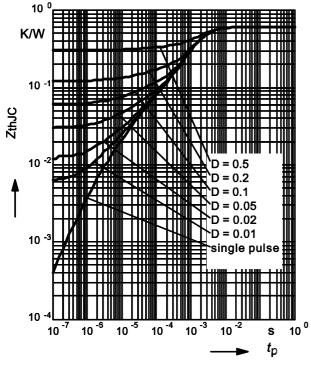
 $P_{\text{tot}} = f(T_{\text{C}})$



3 Transient thermal impedance

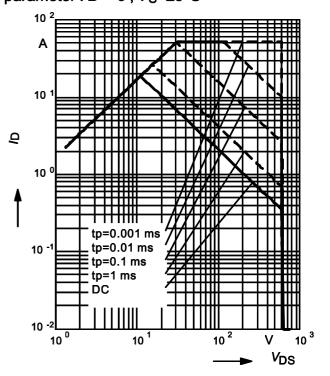
 $Z_{\text{thJC}} = f(t_{\text{p}})$

parameter: $D = t_p/T$



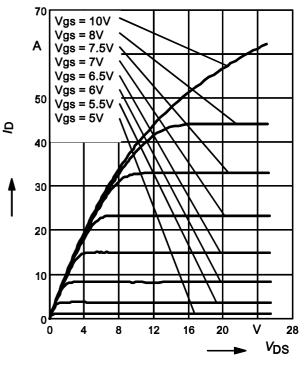
2 Safe operating area

 $I_{\rm D} = f(V_{\rm DS})$ parameter : D = 0 , $T_{\rm C}=25^{\circ}{\rm C}$



4 Typ. output characteristic

 $I_D = f(V_{DS}); T_j=25^{\circ}C$ parameter: $t_p = 10 \ \mu s, V_{GS}$



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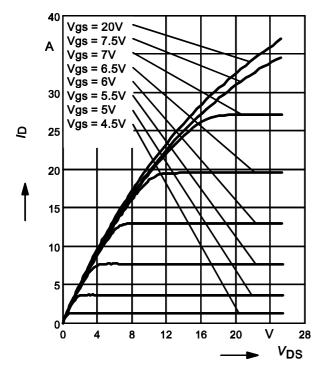
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5 Typ. output characteristic

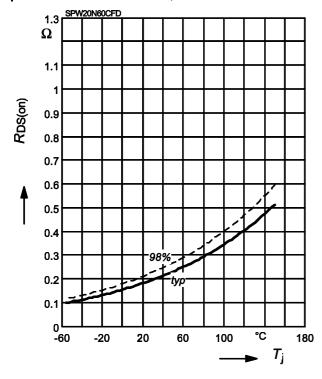
 $I_D = f(V_{DS}); T_j=150^{\circ}C$ parameter: $t_p = 10 \ \mu s, V_{GS}$



7 Drain-source on-state resistance

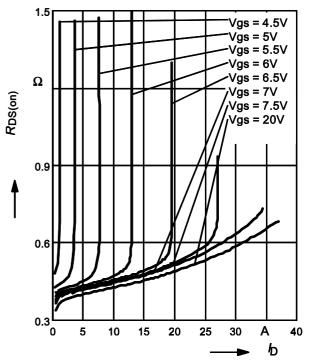
 $R_{\text{DS(on)}} = f(T_{j})$

```
parameter : I_D = 13.1 A, V_{GS} = 10 V
```



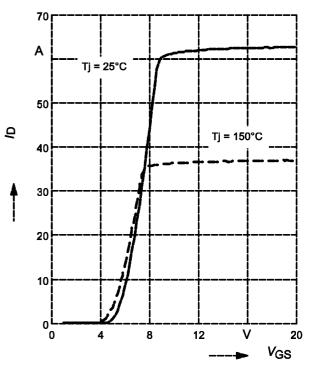
6 Typ. drain-source on resistance

R_{DS(on)}=ƒ(I_D) parameter: T_j=150°C, V_{GS}



8 Typ. transfer characteristics

 $I_D = f(V_{GS}); V_{DS} \ge 2 \times I_D \times R_{DS(on)max}$ parameter: $t_p = 10 \ \mu s$



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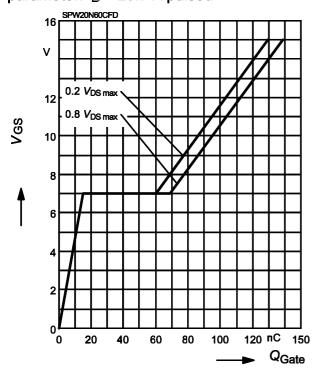
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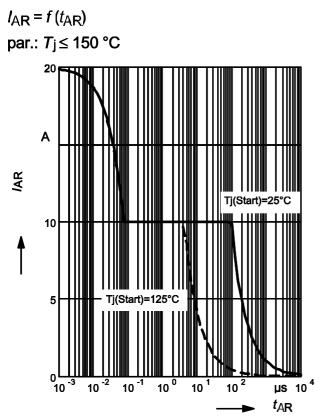
9 Typ. gate charge

 $V_{\rm GS} = f (Q_{\rm Gate})$

parameter: $I_{\rm D}$ = 20.7 A pulsed



11 Avalanche SOA

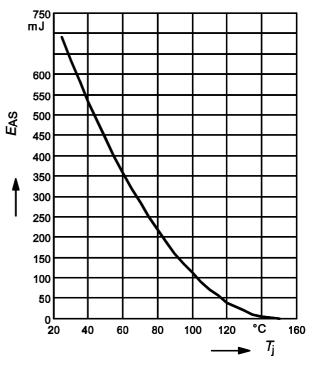


10 Forward characteristics of body diode

 $I_{\rm F} = f(V_{\rm SD})$ parameter: T_i , tp = 10 µs 10 2_SPW20N600 Α 10 Ŧ 10 0 = 25 °C typ = 150 °C typ 25 °C (98%) 150 °C (98%) 10 -1 ۷ 0 0.4 0.8 1.2 1.6 2 2.4 3 V_{SD}

12 Avalanche energy

 $E_{AS} = f(T_j)$ par.: $I_D = 10 \text{ A}, V_{DD} = 50 \text{ V}$





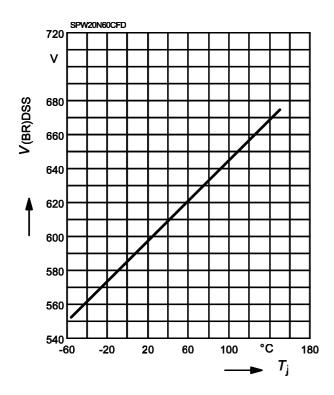
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13 Drain-source breakdown voltage

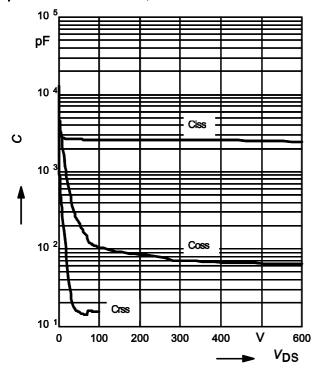
 $V_{(BR)DSS} = f(T_j)$



15 Typ. capacitances

 $C = f(V_{\text{DS}})$

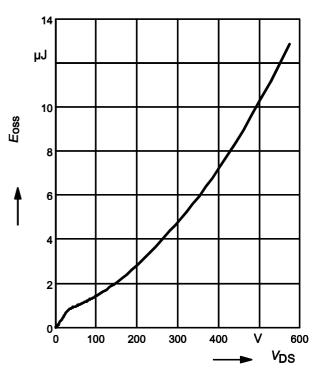
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parameter: VGS=0V, f=1 MHz
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14 Avalanche power losses

P_{AR} = f(f) parameter: E_{AR}=1mJ

16 Typ. C_{oss} stored energy $E_{\text{oss}}=f(V_{\text{DS}})$



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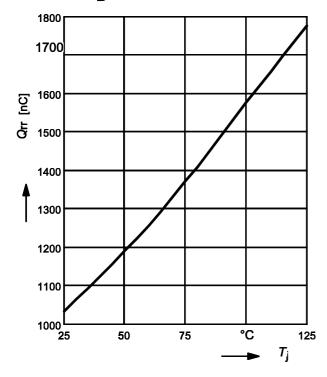
f



17 Typ. reverse recovery charge

 $Q_{rr} = f(T_J)$

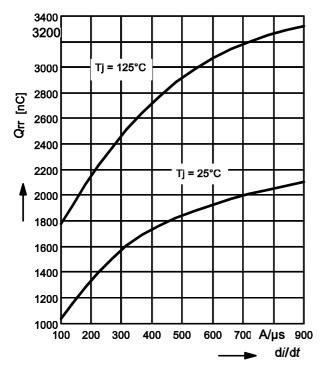
parameter: I_D = 20.7A



19 Typ. reverse recovery charge

 $Q_{rr} = f(di/dt)$

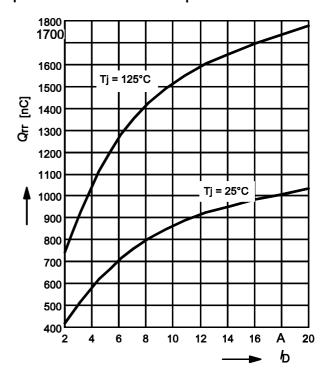
parameter: $I_D = 20.7 \text{ A}$



18 Typ. reverse recovery charge

 $Q_{rr} = f(I_D)$

parameter: di/dt = 100 A/us



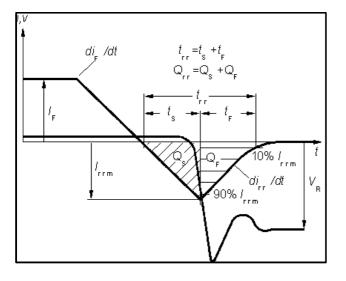


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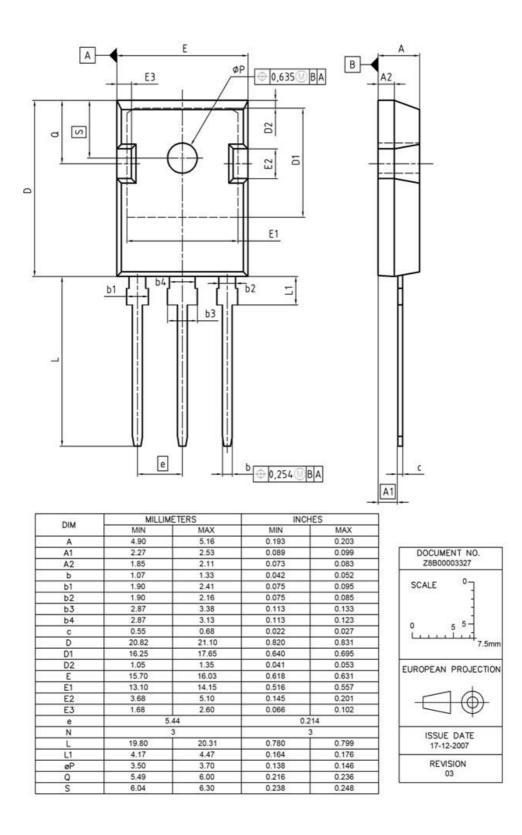


Definition of diodes switching characteristics





PG-TO-247-3-1







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New package outlines TO-247

1 New package outlines TO-247

Assembly capacity extension for CoolMOSTM technology products assembled in lead-free package PG-TO247-3 at subcontractor ASE (Weihai) Inc., China (Changes are marked in blue.)

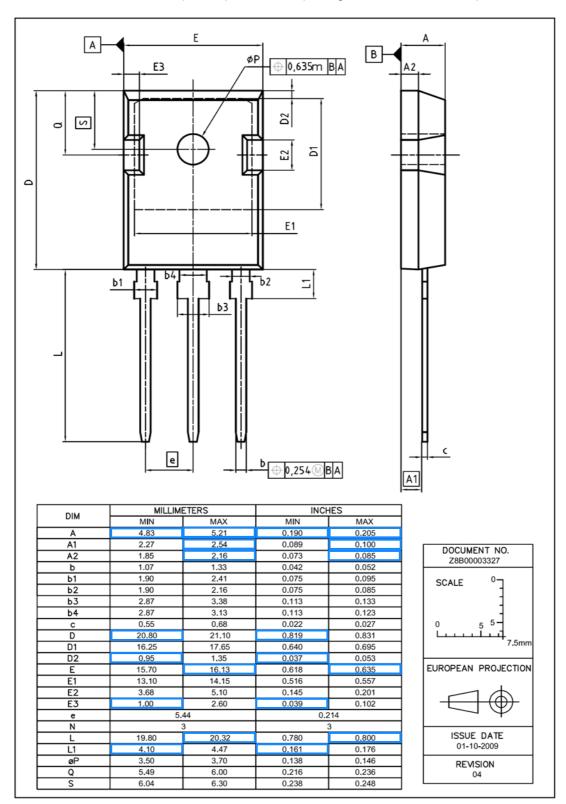


Figure 1 Outlines TO-247, dimensions in mm/inches

Mouser Electronics

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